



Material Content Data Sheet



Sales Product Name		IPG20N06S4L-26A		Issued		24. January 2018		
MA#		MA001663546						
Package		PG-TDSON-8-10		Weight*		98.55 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.567	1.59	1.59	15898	15898
leadframe	non noble metal	iron	7439-89-6	0.046	0.05		471	
	inorganic material	phosphorus	7723-14-0	0.014	0.01		141	
	non noble metal	copper	7440-50-8	46.380	47.06	47.12	470644	471259
wire	non noble metal	aluminium	7429-90-5	0.724	0.74	0.74	7351	7351
encapsulation	organic material	carbon black	1333-86-4	0.091	0.09		922	
	plastics	epoxy resin	-	6.451	6.55		65459	
	inorganic material	silicondioxide	60676-86-0	38.886	39.46	46.10	394598	460979
leadfinish	non noble metal	tin	7440-31-5	1.396	1.42	1.42	14170	14170
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		15	
	non noble metal	nickel	7440-02-0	0.603	0.61	0.61	6120	6135
solder	noble metal	silver	7440-22-4	0.060	0.06		605	
	non noble metal	tin	7440-31-5	0.048	0.05		484	
	non noble metal	lead	7439-92-1	2.278	2.31	2.42	23119	24208
heatspreader	non noble metal	copper	7440-50-8	0.000	0.00		1	
	non noble metal	iron	7439-89-6	0.000	0.00		1	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.00	1	0
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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